

General Description

The WSD30100DN56 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD30100DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

BVDSS	RDSON	RDSON ID	
30V	$3.3 m\Omega$	100A	

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN5X6-8 Pin Configuration



Absolute Maximum Ratings

Symbol Parameter		Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	100	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	56	Α
I _{DM}	Pulsed Drain Current ²	140	Α
EAS	Single Pulse Avalanche Energy ³	45	mJ
I _{AS}	Avalanche Current	30	А
P _D @T _C =25°C	Total Power Dissipation⁴	46.3	W
T _{STG}	Storage Temperature Range	-55 to 175	$^{\circ}$
T _J Operating Junction Temperature Range -55 to 175		-55 to 175	$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		2.7	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.0213		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A		3.3	4	mΩ
R _{DS(ON)}	Static Dialii-Source Off-Resistance	V _{GS} =4.5V , I _D =15A		4.6	6.2	1117.5
V _{GS(th)}	Gate Threshold Voltage	\/ -\/ -250A	1.5	1.8	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.73		mV/℃
	Drain Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		28		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.0	2.0	Ω
Q_g	Total Gate Charge (4.5V)			9.2		
Q_gs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =20A		6		nC
Q _{gd}	Gate-Drain Charge			2		1
T _{d(on)}	Turn-On Delay Time			14.3		
T _r	Rise Time	V _{DD} =12V , V _{GEN} =10V ,		26		no
T _{d(off)}	Turn-Off Delay Time	R_G =2.9 Ω , I_D =5.7A, R_L =2.1 Ω		24		ns
T _f	Fall Time			4.4		
Ciss	Input Capacitance			1350		
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		900		pF
C _{rss}	Reverse Transfer Capacitance			65		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.1mH , I _{AS} =30A	30			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			20	Α
I _{SM}	Pulsed Source Current ^{2,6}	V _G =V _D =0V , Force Current			140	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =20A , T _J =25℃			1	V

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t<10sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =30A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

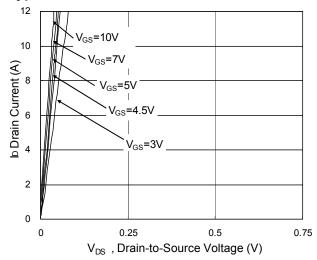
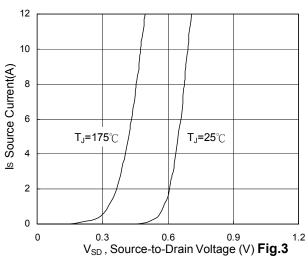


Fig.1 Typical Output Characteristics



Forward Characteristics of Reverse

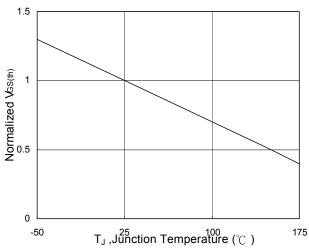


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

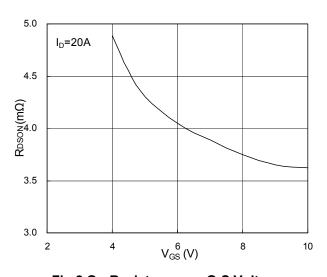


Fig.2 On-Resistance vs. G-S Voltage

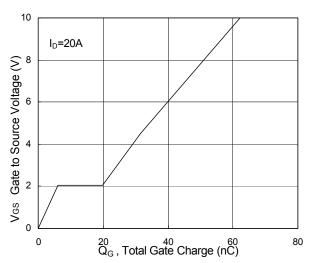


Fig.4 Gate-charge Characteristics

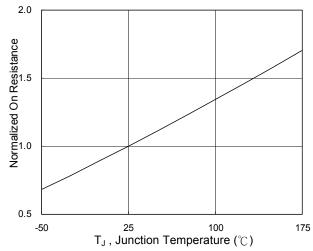
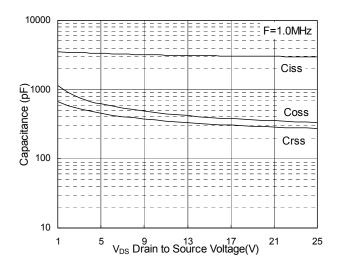


Fig.6 Normalized R_{DSON} vs. T_J





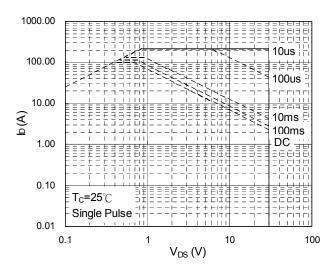


Fig.7 Capacitance

Fig.8 Safe Operating Area

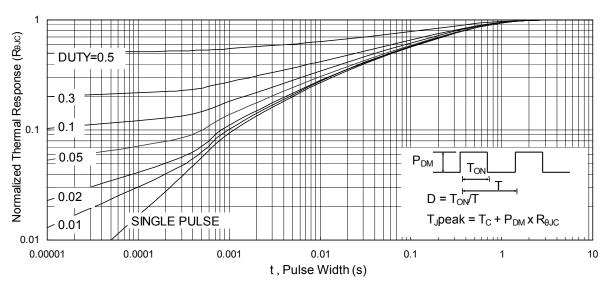


Fig.9 Normalized Maximum Transient Thermal Impedance

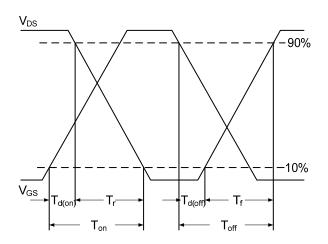


Fig.10 Switching Time Waveform

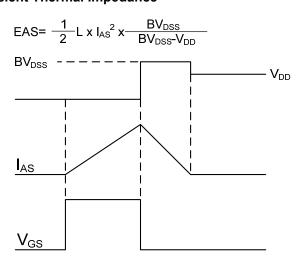


Fig.11 Unclamped Inductive Switching Wave



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